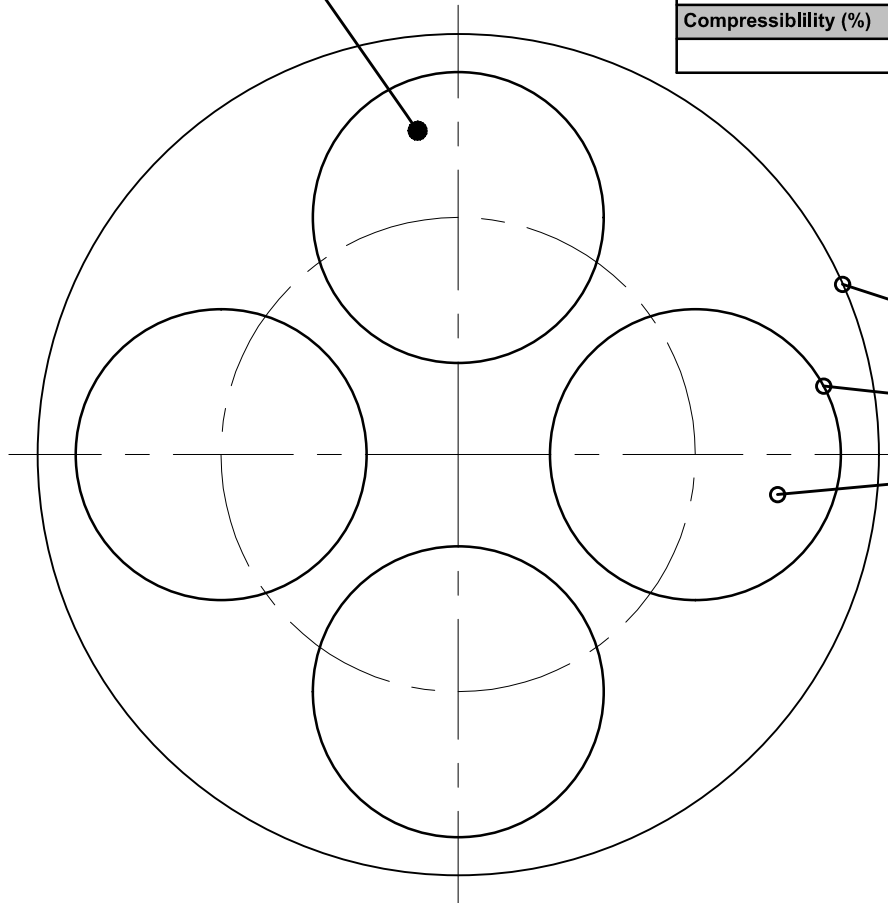


REVISIONS				
REV.	ECN #	DESCRIPTION	DATE	BY
A	Cxxxx	INITIAL RELEASE	xx/xx/xx	MLK

### Template Pad Material Guide

Pad Material	Napcon-1000DM	Napcon-1000	Napcon-7000	Napcon-1450	BP-107
Pad Surface:	Machined	Buffed	Buffed	Non-Buffed	Buffed
Film Thickness (µm)	525	520	590	610	390
Film Thickness Tol. (µm)	± 15	± 20	± 30	± 50	± 30
Pore Height (µm)	300-390	300-390	300-390	N/A	100-190
Pore Diameter (µm)	35-55	35-55	33-53	N/A	41-51
Pore Rate (%)	18-28	18-28	20-30	N/A	18-28
Compressibility (%)	27-37	27-37	6-20	3-7	13-23


SHAPE IS PER  
CUSTOMER SPECIFICATION



### Template Information Requested

Complete any item known		
	Metric Dimensions	Inch Dimensions
Template Outside Diameter		
Wafer Diameter with Tolerance		
Wafer Finished Thickness		
Operating Pressure		
Operating Temperature		
Wafer Material		
Number of Pockets		

- NOTES:  
1. CUSTOMER -  
2. C OF C REQUIRED, SEE TESTSPECT001

ITEM	PART NO.	QUAN.	MANUFACTURE - DESCRIPTION
A	Txxxx	1	PAD MATERIAL - NAPCON xxxxx POCKET DEPTH - x,xxxx*±0.0015 [xxxx.xµm±38.10µm]
PARTS LIST			
CONFIDENTIAL - PROPERTY OF			
<small>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES</small>  <small>DECIMAL: ±0.010 (±0.2540)</small> <small>FRACTIONAL: ±1/64</small> <small>ANGULAR: ±0°30'</small>		<small>MATERIAL:</small> xxx' SQUARE LAMITEX	 APPR. xxx DATE xx/xx/xx BY M KUGLER DATE xx/xx/xx
			PART TEMPLATE, POLISHING UNIT f / xxxxx MACHINE